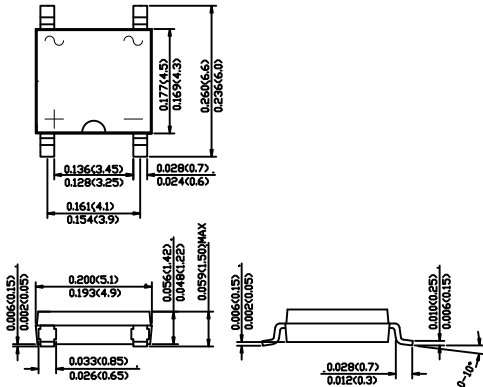


# ABS2 THRU ABS10

## SINGLE PHASE GLASS PASSIVATED BRIDGE RECTIFIERS

Voltage Range - 200 to 1000 Volts    Current - 0.8/1.0 Ampere

### ABS



Dimensions in inches and (millimeters)

### FEATURES

- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at 5 lbs., (2.3kg) tension
- ◆ Small size, simple installation
- ◆ Leads solderable per MIL-STD-202, Method 208
- ◆ High surge current capability
- ◆ Glass passivated chip junction

### MECHANICAL DATA

**Case:** Molded plastic body

**Terminals:** Plated leads solderable per MIL-STD-750, Method 2026

**Polarity:** Polarity symbols marked on case

**Mounting Position:** Any

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

	SYMBOLS	ABS2	ABS4	ABS6	ABS8	ABS10	UNITS
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	200	400	600	800	1000	VOLTS
Maximum RMS voltage	V <sub>RMS</sub>	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	V <sub>DC</sub>	200	400	600	800	1000	VOLTS
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	I <sub>F(AV)</sub>	0.8 1.0					Amps
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	30					Amps
Maximum instantaneous forward voltage drop per leg at 0.4A	V <sub>F</sub>	0.95					Volts
Maximum DC reverse current    T <sub>A</sub> =25°C at rated DC blocking voltage    T <sub>A</sub> =125°C	I <sub>R</sub>	10 150					uA uA
Typical thermal resistance(NOTE 3)	Rθ <sub>JL</sub>	25					°C/W
	Rθ <sub>JA</sub>	80					
Operating temperature range	T <sub>J</sub>	-55 to +150					°C
storage temperature range	T <sub>STG</sub>	-55 to +150					°C

NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads

2.On aluminum substrate P.C.B. with on area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad

3.Thermal resistance form junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

## RATINGS AND CHARACTERISTIC CURVES ABS2 THRU ABS10

FIG.1 TYPICAL FORWARD CHARACTERISTICS

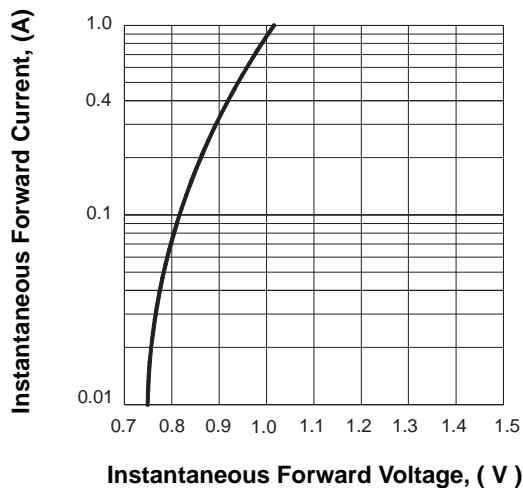


FIG.2 FORWARD DERATING CURVE

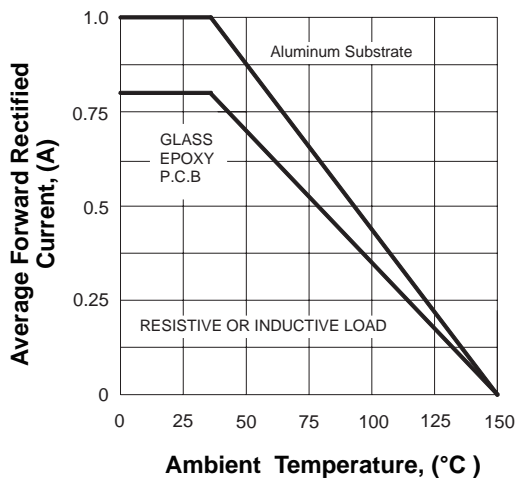


FIG.3 TYPICAL REVERSE CHARACTERISTICS

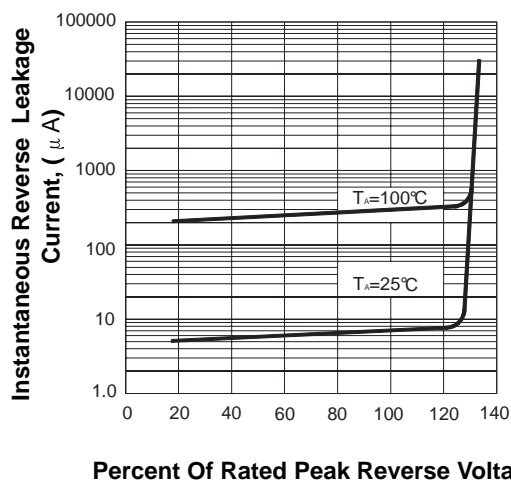


FIG.4 PEAK FORWARD SURGE CURRENT

